

FOR IMMEDIATE RELEASE

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NEXTREME AND LOCKHEED MARTIN ANNOUNCE COOPERATION AGREEMENT FOR DEVELOPMENT OF NEXT GENERATION THERMAL AND POWER MANAGEMENT SOLUTIONS

DURHAM, N.C. (July 28, 2009) — Nextreme Thermal Solutions, the leader in microscale thermal and power management products for the electronics industry, and Lockheed Martin [NYSE: LMT], have entered into a cooperation agreement to develop new products based on Nextreme's thin-film thermoelectric materials.

The agreement allows Lockheed Martin to use Nextreme's thin-film thermoelectric products and thermal and power management design services in solutions it is developing for government and civil applications.

"Lockheed Martin is proud to enter into this cooperation agreement with Nextreme," said Brad Pietras, Director of Nanotechnology Programs at Lockheed Martin. "The agreement gives us the opportunity to offer our customers new and differentiated products for enhanced thermal and power management."

"Lockheed Martin is a global leader and engaging with them is a tremendous step forward for Nextreme," said Jesko von Windheim, CEO of Nextreme. "They represent leading-edge technology and offer an exceptional channel into the government sector, both of which can accelerate the development of next generation products."

Nextreme's team of engineers offers thermal modeling, design and engineering services to deliver fully optimized microscale thermal and power management solutions using standard and customized products.

Nextreme uses its breakthrough thermal bump technology to produce discrete and integrated cooling and power generation devices. Nextreme currently offers several thermoelectric coolers, such as the OptoCooler HV14 and UPF40, that are capable of cooling and heating in ranges from 0.4 watts to 4 watts, with plans to provide higher heat pumping in the near future. Modules for electronics cooling and power generation are available for order now and pricing is available upon request.

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About Lockheed Martin

Headquartered in Bethesda, Md., Lockheed Martin is a global security company that employs about 146,000 people worldwide and is principally engaged in the research, design, development, manufacture, integration and sustainment of advanced technology systems, products and services. The corporation reported 2008 sales of \$42.7 billion.

About Nextreme Thermal Solutions™, Inc.

Nextreme Thermal Solutions designs and manufactures microscale thermal and power management products for the electronics, telecommunications, semiconductor, consumer, and aerospace/government industries. The company uses breakthrough thin-film thermoelectric material to embed cooling, temperature control and power generation capabilities into the widely accepted copper pillar bumping process used in high-volume electronic packaging. Nextreme's headquarters and manufacturing facility are based near Research Triangle Park, North Carolina.

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